



## Material Content Data Sheet



<b>Sales Product Name</b>		IPC100N04S5-1R7		<b>Issued</b>		30. July 2019		
<b>MA#</b>		MA002905722						
<b>Package</b>		PG-TDSON-8-34		<b>Weight*</b>		112.73 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	1.077	0.96	0.96	9551	9551
leadframe	inorganic material	phosphorus	7723-14-0	0.016	0.01		141	
	non noble metal	iron	7439-89-6	0.053	0.05		469	
wire	non noble metal	copper	7440-50-8	52.842	46.86	46.92	468748	469358
	noble metal	gold	7440-57-5	0.044	0.04	0.04	389	389
encapsulation	organic material	carbon black	1333-86-4	0.075	0.07		668	
	plastics	epoxy resin	-	5.947	5.28		52757	
leadfinish	inorganic material	silicondioxide	60676-86-0	31.618	28.05	33.40	280478	333903
	non noble metal	tin	7440-31-5	1.574	1.40	1.40	13961	13961
plating	noble metal	silver	7440-22-4	0.209	0.19	0.19	1856	1856
solder	non noble metal	tin	7440-31-5	0.030	0.03		262	
	noble metal	silver	7440-22-4	0.037	0.03		327	
heat sink clip	non noble metal	lead	7439-92-1	1.410	1.25	1.31	12508	13097
	inorganic material	phosphorus	7723-14-0	0.005	0.00		45	
clip plating	non noble metal	iron	7439-89-6	0.017	0.01		149	
	non noble metal	copper	7440-50-8	16.828	14.93	14.94	149273	149467
heatspreader	noble metal	silver	7440-22-4	0.639	0.57	0.57	5668	5668
heatspreader	inorganic material	phosphorus	7723-14-0	0.000	0.00		1	
	non noble metal	iron	7439-89-6	0.000	0.00		3	
*deviation	non noble metal	copper	7440-50-8	0.310	0.27	0.27	2746	2750
						Sum in total:	100.00	

### Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

Company	Infineon Technologies AG
Address	81726 München
Internet	www.infineon.com